



# N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>d</sup>	Q <sub>g</sub> (Typ.)				
	0.028 at V <sub>GS</sub> = 4.5 V	7.9					
20	0.032 at V <sub>GS</sub> = 2.5 V	7.4	6.7 nC				
	0.038 at V <sub>GS</sub> = 1.8 V	6.8					

#### **FEATURES**

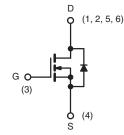
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

#### **APPLICATIONS**

- DC/DC Converters
- Boost Converters
- Load Switch



N-Channel MOSFET

		Top Vie		
T	D	1	6	D D
3 mm	D□	2	5	D D
	G	3	4	∭ s
	<b> </b>	2.85 mr	m <b>–</b>	-



Ordering Information: Si3460DDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	20 ± 8		
Gate-Source Voltage		V <sub>GS</sub>			
	T <sub>C</sub> = 25 °C		7.9		
Continuous Dusin Comment (T. 150 °C)	T <sub>C</sub> = 70 °C	1 .	6.3		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	6.2 <sup>a, b</sup>		
	T <sub>A</sub> = 70 °C		5.0 <sup>a, b</sup>	Α	
Pulsed Drain Current		I <sub>DM</sub>	20		
Continuous Course Dunin Diada Courset	T <sub>C</sub> = 25 °C		2.2		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	1.4 <sup>a, b</sup>		
Avalanche Current		I <sub>AS</sub>	8		
Single Avalanche Energy		E <sub>AS</sub>	3.2	mJ	
	T <sub>C</sub> = 25 °C		2.7		
Manifestor Brown Biration	T <sub>C</sub> = 70 °C		1.7		
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.7 <sup>a, b</sup>	W	
	T <sub>A</sub> = 70 °C		1.1 <sup>a, b</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Tempera		260			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 5 s	R <sub>thJA</sub>	61	74	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	38	46	O/W	

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 120  $^{\circ}\text{C/W}.$
- d. Based on  $T_C = 25$  °C.

# Si3460DDV

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				1		
Drain-Source Breakdown Voltage	$V_{DS}$	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	S/T <sub>J</sub>		21		
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 2.6		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu\text{A}$	0.4		1.0	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
Zero Oeto Vella de Busin Occurrent		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
	(* /	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 5.1 A		0.023	0.028	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V, } I_D = 4.7 \text{ A}$		0.027	0.032	Ω
	()	$V_{GS} = 1.8 \text{ V, } I_D = 2.5 \text{ A}$		0.031	0.038	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.1 A		35		S
Dynamic <sup>b</sup>		-				
Input Capacitance	C <sub>iss</sub>			666		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		93		
Reverse Transfer Capacitance	C <sub>rss</sub>	30		41		
·	Q <sub>g</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 8 V, I <sub>D</sub> = 5 A		12	18	nC
Total Gate Charge				6.7	10.1	
Gate-Source Charge		$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		0.95		
Gate-Drain Charge	Q <sub>gd</sub>			0.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.1	4.2	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			6	12	
Rise Time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_1 = 2 \Omega$		11	20	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		21	32	
Fall Time	t <sub>f</sub>	•		8	16	
Turn-On Delay Time	t <sub>d(on)</sub>			5	10	
Rise Time	t <sub>r</sub>			12	18	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 8 \text{ V}, R_q = 1 \Omega$		19	29	
Fall Time	t <sub>f</sub>	Ç		8	16	
Drain-Source Body Diode Characteristic						
Continuous Source-Drain Diode Current I <sub>S</sub>		T <sub>C</sub> = 25 °C			2.2	
Pulse Diode Forward Current	I <sub>SM</sub>	<u> </u>			20	Α
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 5 A, V <sub>GS</sub> = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	5 . 40		11	20	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			3	6	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		7	-	ns
Reverse Recovery Rise Time	t <sub>b</sub>		<u> </u>	4		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %

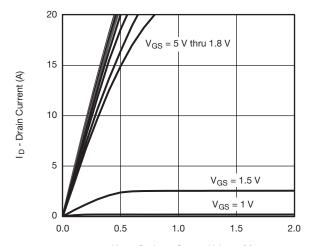
b. Guaranteed by design, not subject to production testing.

1.2

1.5

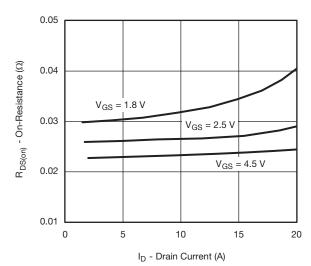


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

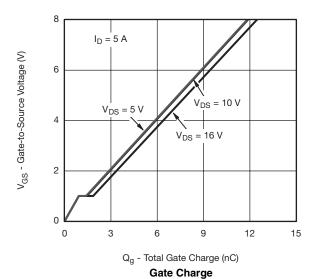


 $V_{\mbox{\scriptsize DS}}$  - Drain-to-Source Voltage (V)





On-Resistance vs. Drain Current and Gate Voltage



 $T_{\rm C} = 25\,^{\circ}{\rm C}$ 

0.6

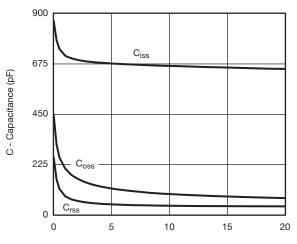
5

0.0

0.3

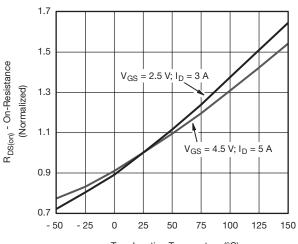
 $V_{GS}$  - Gate-to-Source Voltage (V)

#### **Transfer Characteristics**



V<sub>DS</sub> - Drain-to-Source Voltage (V)

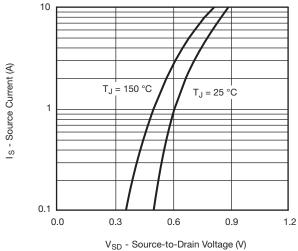
#### Capacitance



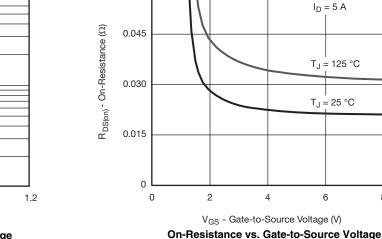
 $\label{eq:TJ-Junction} T_{J} \text{ - Junction Temperature (°C)}$  On-Resistance vs. Junction Temperature

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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

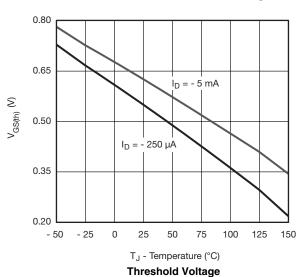


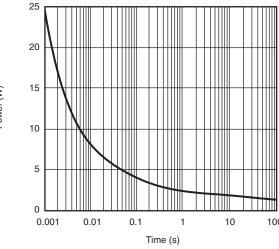
Source-Drain Diode Forward Voltage



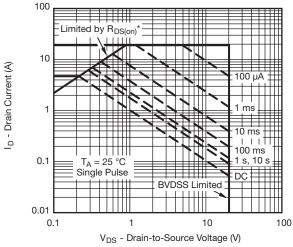
0.060

On-Resistance vs. Gate-to-Source Voltage





Single Pulse Power (Junction-to-Ambient)

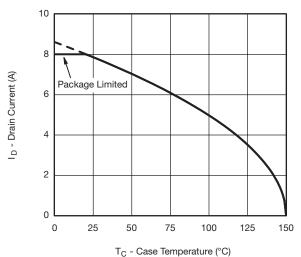


\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient

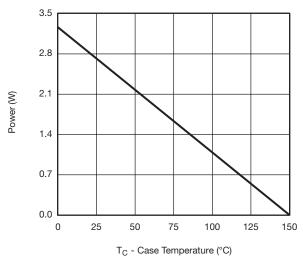


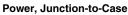
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

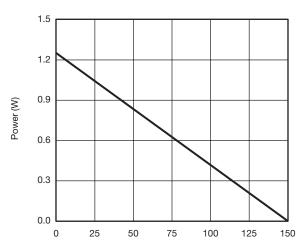


#### Current Devetine\*

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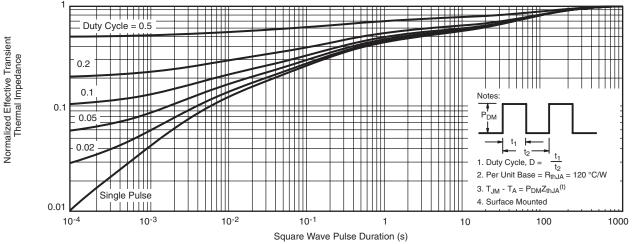
T<sub>A</sub> - Ambient Temperature (°C) **Power, Junction-to-Ambient** 

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

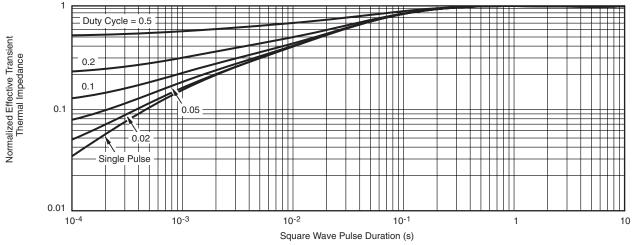
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#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

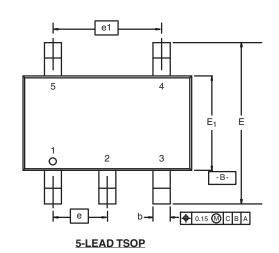
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppq?66572">www.vishay.com/ppq?66572</a>.

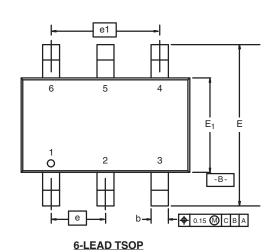


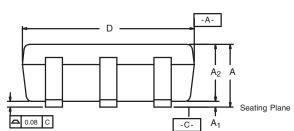


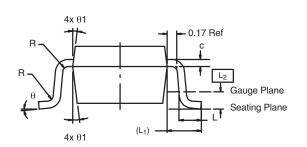
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 









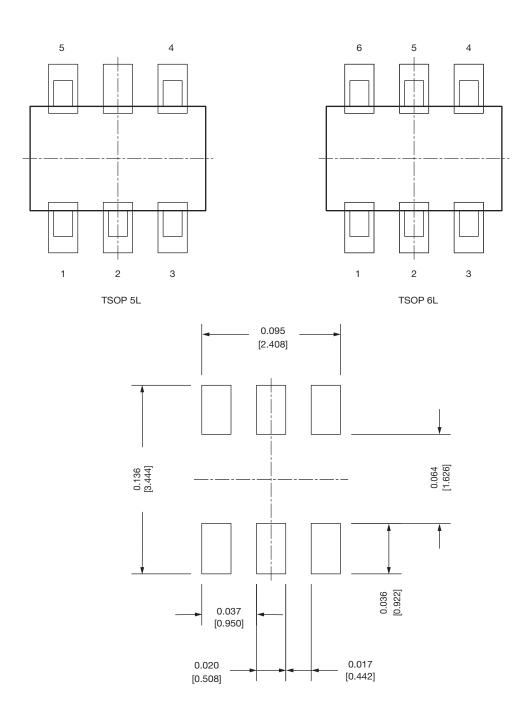
	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>	0.60 Ref			0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
$\theta_1$	7° Nom 7° Nom						
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200

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# Recommended Land Pattern For TSOP-5L / TSOP-6L



#### Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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